CBCS SCHEME

TICNI		
USN		

15NT73

## Seventh Semester B.E. Degree Examination, July/August 2021 MEMS and NEMS

Time: 3 hrs.

Max. Marks: 80

Note: Answer any FIVE full questions.

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1	a. Enumerate the concept of miniaturization and list the benefits.	(08 Marks
	b. Discuss the various steps involved in fabrication of IC's.	(08 Marks
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2	a. Write a note on micro-sensors and micro actuators.	(08 Marks)
	b. Explain briefly about MEMS packages.	(08 Marks)
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3	a. Define transducer and explain the working of	
	i) Capacitive transducer ii) Optical waveguide transducer.	(09 Marks)
	b. Explain the working of schottky diode based transducer	(07 Marks)
4	a. Briefly about:	
	i) Quartz crystal imbalance ii) Film bulk acoustic wave resonator.	(10 Marks)
	b. Explain importance of cantilever based transducer.	(06 Marks)
5	a. With a sketch, explain surface and Bulk micro machining.	(10 Marks)
	b. List and explain various etching methods.	(06 Marks)
6	a. With a sketch, explain the concept of photolithography.	(10 Marks)
	b. Define piezoelectric effect, and explain the various mechanisms involved in it.	(06 Marks)
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7	<ul><li>a. Explain the concept of Reliability and stability.</li><li>b. Discuss briefly about the various MEMS failure mechanism.</li></ul>	(06 Marks)
	b. Discuss orienty about the various wiews famure mechanism.	(10 Marks)
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8	a. Enumerate the concept of CMOS and transmitters.	(06 Marks)
	<ul><li>b. Write a note on: i) Traceability ii) Calibration.</li><li>c. Discus the working of signal amplifier.</li></ul>	(06 Marks)
	C. Discus the working of signal amplifier.	(04 Marks)
0	Define NEMC Francis News weeks a CNEMO	
9	<ul><li>a. Define NEMS, Explain Nano machining of NEMS.</li><li>b. List and explain the steps involved in fabrication of NEMS.</li></ul>	(06 Marks)
	b. Elst and explain the steps involved in labrication of IVEWIS.	(10 Marks)
10	a. Write a short note on : Stencil lithography ii) Sacrificial etching	(00.75
10	<ul><li>a. Write a short note on : (a) Stencil lithography ii) Sacrificial etching</li><li>b. Explain briefly about future challenges and applications of NEMS.</li></ul>	(08 Marks)
	2. Dapam oriony dood facule chancinges and applications of 14151415.	(08 Marks)
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Important Note: 1. On completing your answers, compulsorily draw diagonal cross lines on the remaining blank pages.